

2N3819

N-Channel RF Amplifier

- This device is designed for RF amplifier and mixer applications operating up to 450MHz, and for analog switching requiring low capacitance.
- Sourced from process 50.



Epitaxial Silicon Transistor

Absolute Maximum Ratings* $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DG}	Drain-Gate Voltage	25	V	
V_{GS}	Gate-Source Voltage	-25	V	
I _D	Drain Current	50	mA	
I _{GF}	Forward Gate Current	10	mA	
T _{STG}	Storage Temperature Range	-55 ~ 150	°C	

^{*} This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Electrical Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	Off Characteristics					
V _{(BR)GSS}	Gate-Source Breakdwon Voltage	$I_G = 1.0 \mu A, V_{DS} = 0$	25			V
I _{GSS}	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$			2.0	nA
V _{GS} (off)	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_{D} = 2.0nA$			8.0	V
V _{GS}	Gate-Source Voltage	$V_{DS} = 15V, I_D = 200\mu A$	-0.5		-7.5	V
On Characteristics						
I _{DSS}	Zero-Gate Voltage Drain Current	$V_{DS} = 15V, V_{GS} = 0$	2.0		20	mA
Small Signal Characteristics						
gfs	Forward Transfer Conductance	$V_{DS} = 15V, V_{GS} = 0, f = 1.0KHz$	2000		6500	μmhos
goss	Output Conductance	V_{DS} = 15V, V_{GS} = 0, f = 1.0KHz			50	μmhos
Уfs	Reverse Transfer Admittance	V_{DS} = 15V, V_{GS} = 0, f = 1.0KHz	1600			μmhos
C _{iss}	Input Capacitance	$V_{DS} = 15V, V_{GS} = 0, f = 1.0KHz$			8.0	pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 15V, V_{GS} = 0, f = 1.0KHz$			4.0	pF

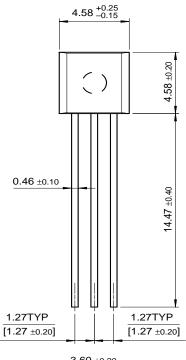
Thermal Characteristics $T_A=25^{\circ}C$ unless otherwise noted

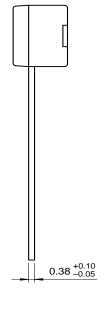
Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W
* Device mounted on FR-4 PCB 1.5" × 1.6" × 0.06"			

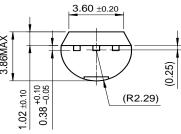
These rating are based on a maximum junction temperature of 150 degrees C.
These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Package Dimensions

TO-92







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